

# RQK0303MGDQA

Silicon N Channel MOS FET  
Power Switching

REJ03G1276-0400

Rev.4.00

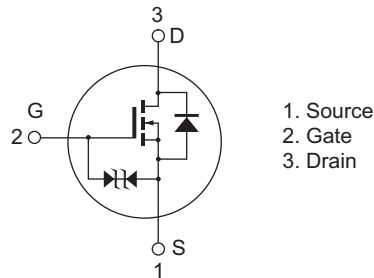
Jun 15, 2006

## Features

- Low on-resistance  
 $R_{DS(on)} = 42 \text{ m}\Omega$  typ ( $V_{GS} = 10 \text{ V}$ ,  $I_D = 1.8 \text{ A}$ )
- Low drive current
- High speed switching
- 4.5 V gate drive

## Outline

RENESAS Package code: PLSP0003ZB-A  
(Package name: MPAK)



Note: Marking is "MG".

## Absolute Maximum Ratings

( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	30	V
Gate to source voltage	$V_{GSS}$	$\pm 20$	V
Drain current	$I_D$	3.7	A
Drain peak current	$I_{D(Pulse)}$ <sup>Note1</sup>	5	A
Body - drain diode reverse drain current	$I_{DR}$	3.7	A
Channel dissipation	$P_{ch}$ <sup>Note2</sup>	0.8	W
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Notes: 1.  $PW \leq 10 \mu\text{s}$ , duty cycle  $\leq 1\%$

2. When using the glass epoxy board (FR-4:  $40 \times 40 \times 1 \text{ mm}$ )

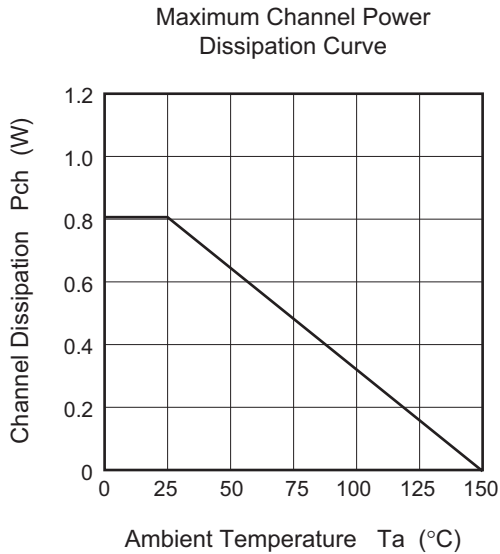
## Electrical Characteristics

(Ta = 25°C)

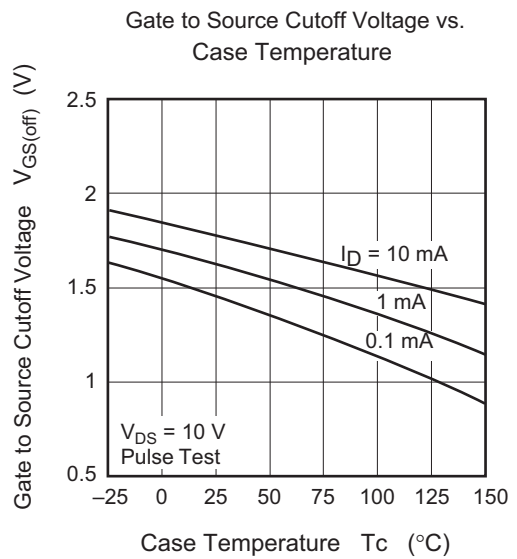
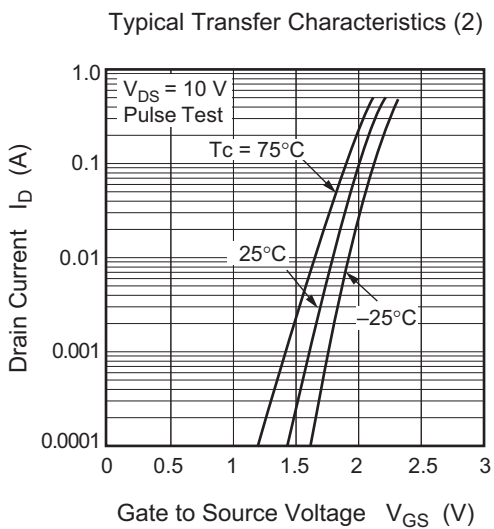
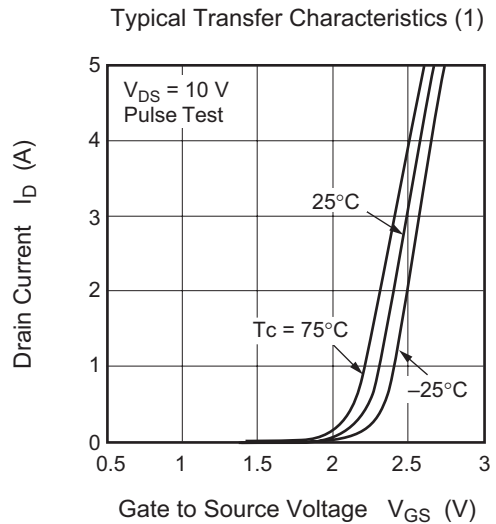
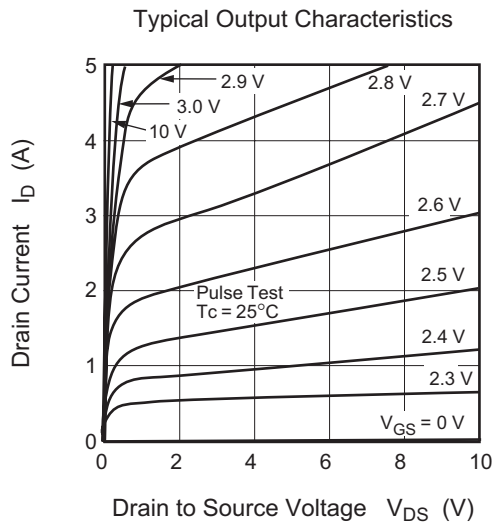
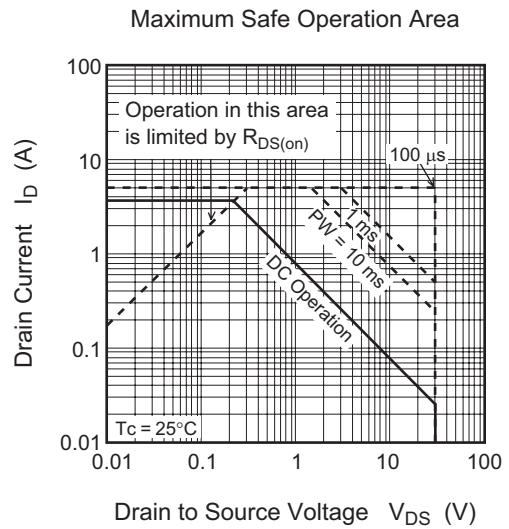
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	$\pm 20$	—	—	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	$\pm 10$	$\mu\text{A}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Drain to source leak current	$I_{DSS}$	—	—	1	$\mu\text{A}$	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.0	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$
Drain to source on state resistance	$R_{DS(on)}$	—	42	53	$\text{m}\Omega$	$I_D = 1.8 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note3}}$
	$R_{DS(on)}$	—	50	70	$\text{m}\Omega$	$I_D = 1.8 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	$ y_{fs} $	3.9	6.5	—	S	$I_D = 1.8 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	$C_{iss}$	—	550	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ $f = 1 \text{ MHz}$
Output capacitance	$C_{oss}$	—	87	—	pF	
Reverse transfer capacitance	$C_{rss}$	—	42	—	pF	
Turn - on delay time	$t_{d(on)}$	—	13	—	ns	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V},$ $R_L = 10 \Omega, R_g = 4.7 \Omega$
Rise time	$t_r$	—	39	—	ns	
Turn - off delay time	$t_{d(off)}$	—	46	—	ns	
Fall time	$t_f$	—	114	—	ns	
Total gate charge	$Q_g$	—	8.9	—	nC	$V_{DD} = 10 \text{ V}, V_{GS} = 10 \text{ V},$ $I_D = 3.7 \text{ A}$
Gate to source charge	$Q_{gs}$	—	1.0	—	nC	
Gate to drain charge	$Q_{gd}$	—	1.3	—	nC	
Body - drain diode forward voltage	$V_{DF}$	—	0.8	—	V	$I_F = 1.5 \text{ A}, V_{GS} = 0^{\text{Note3}}$

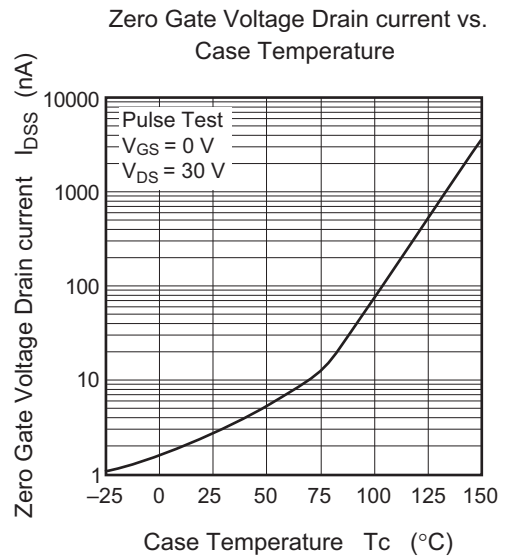
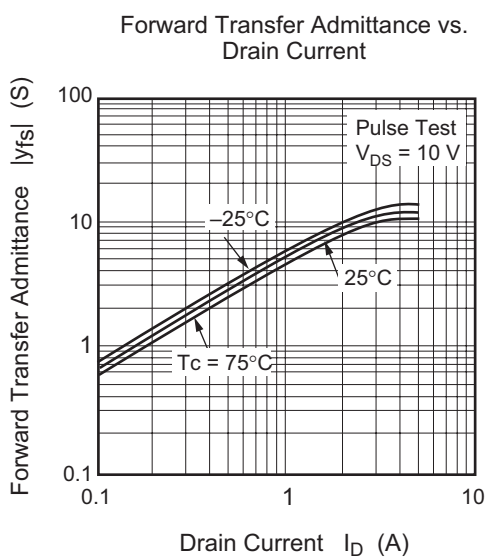
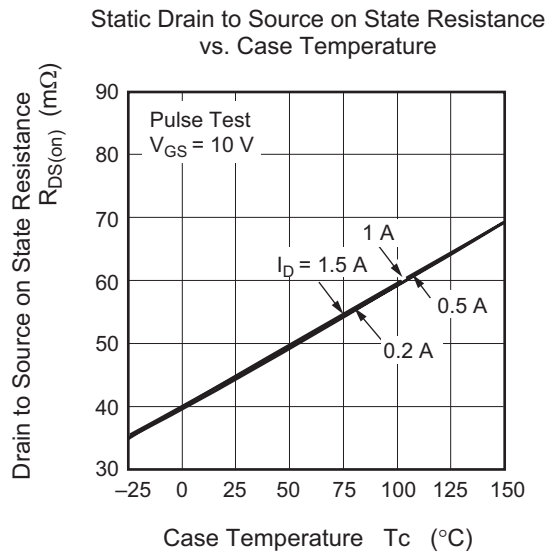
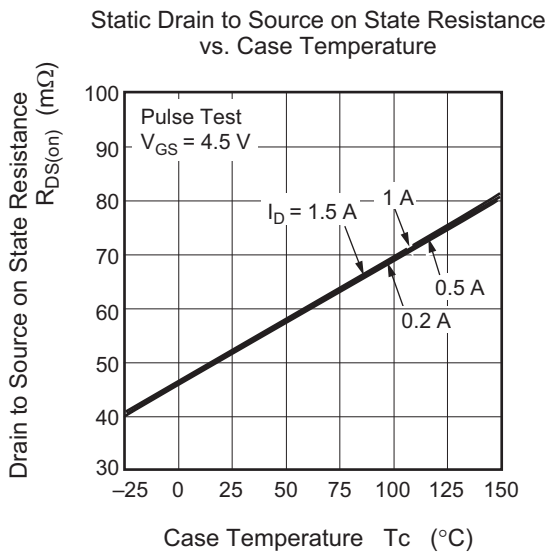
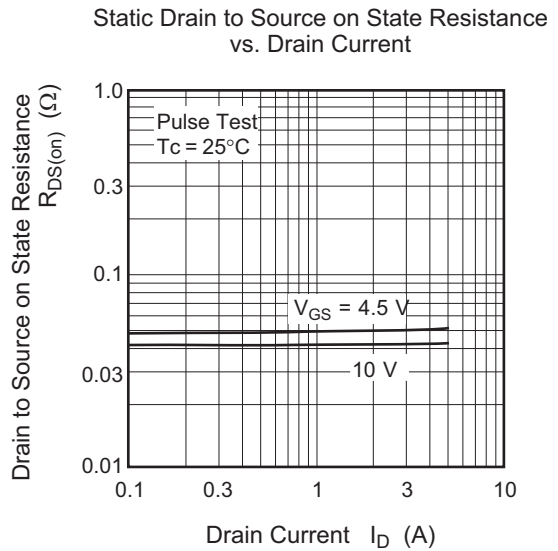
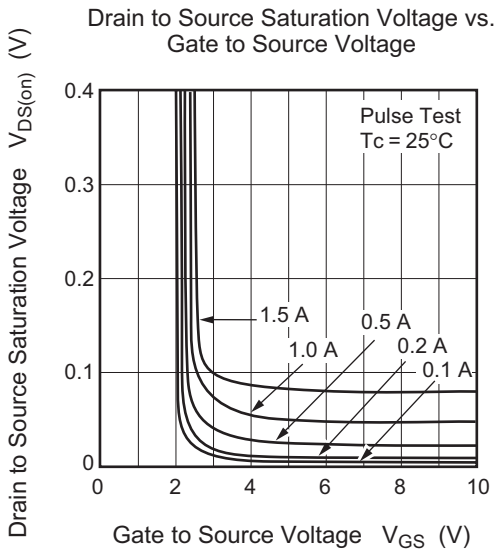
Notes: 3. Pulse test

Main Characteristics

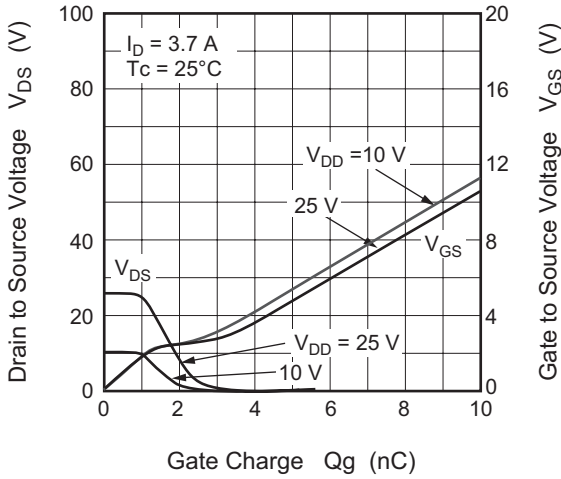


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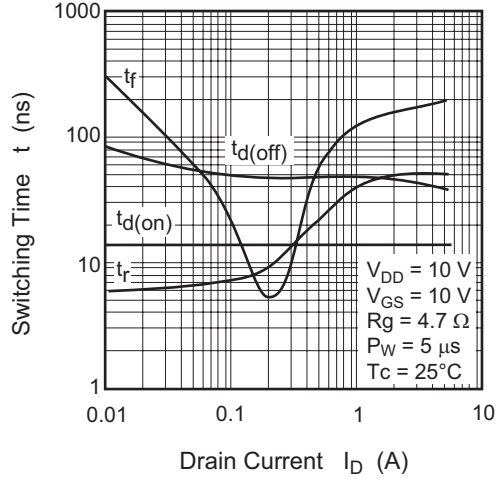




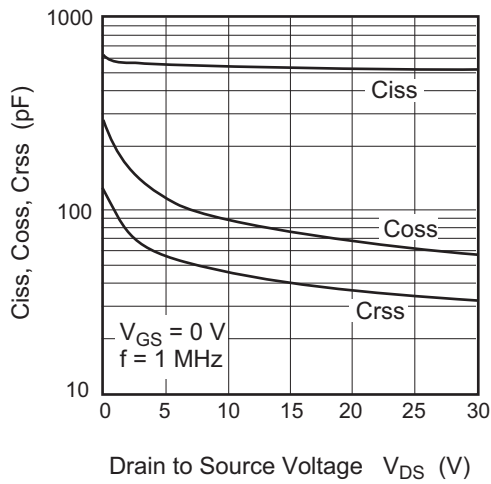
Dynamic Input Characteristics



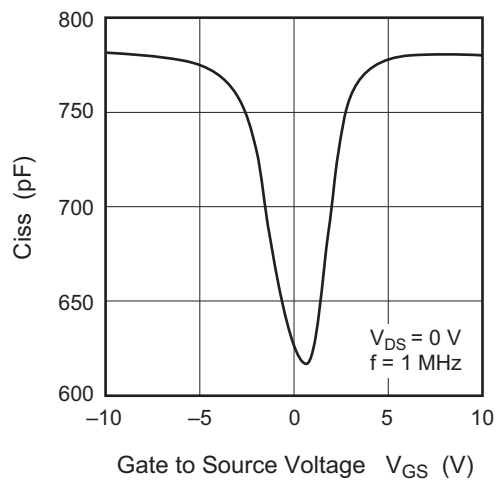
Switching Characteristics



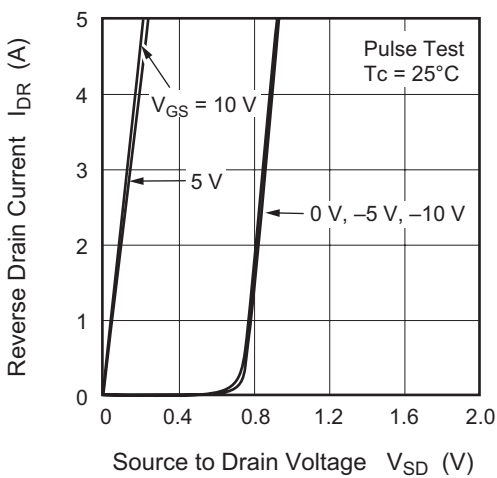
Typical Capacitance vs. Drain to Source Voltage



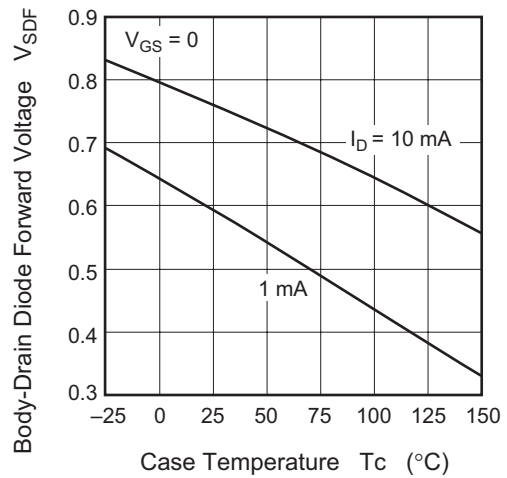
Input Capacitance vs. Gate to Source Voltage



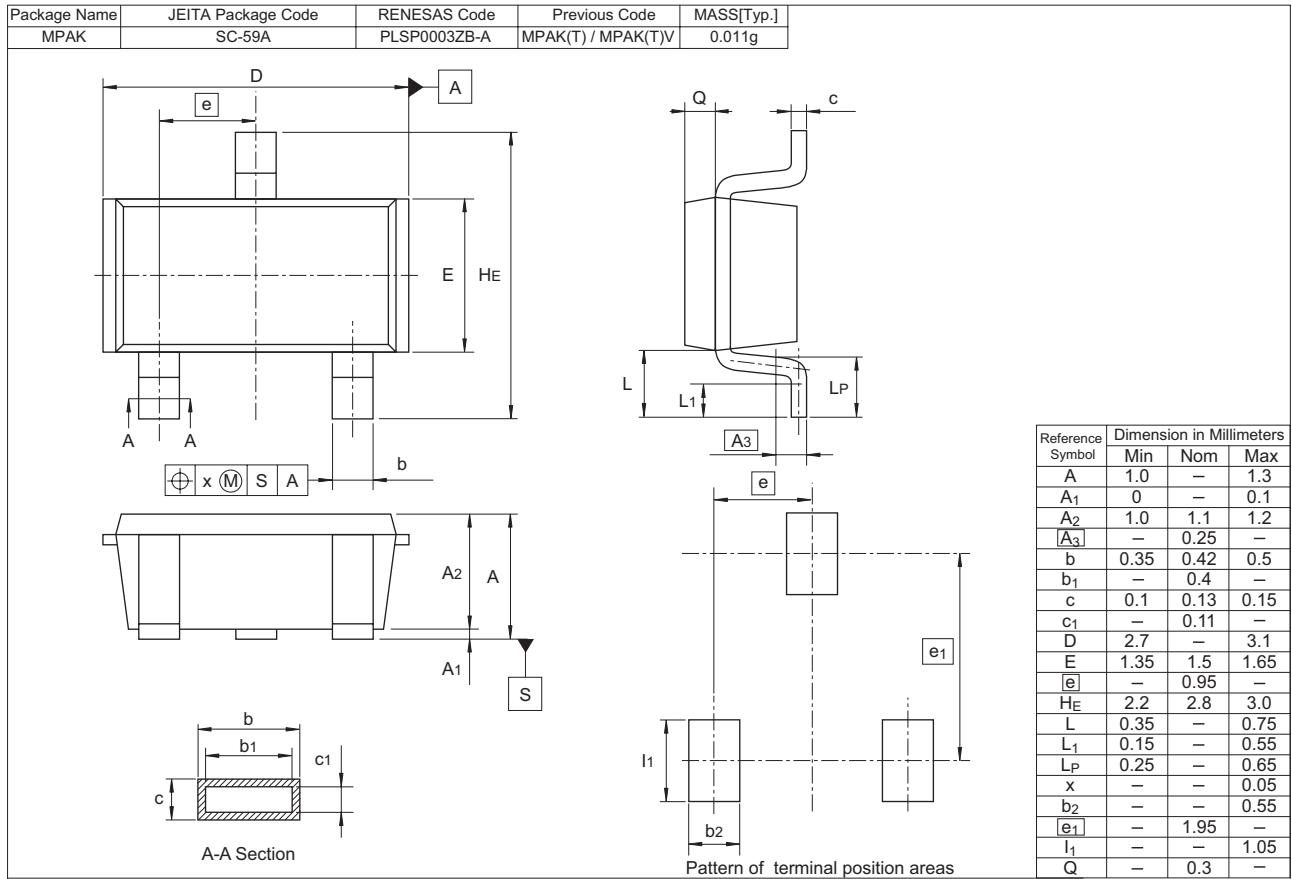
Reverse Drain Current vs. Source to Drain Voltage



Body-Drain Diode Forward Voltage vs. Case Temperature



### Package Dimensions



### Ordering Information

Part Name	Quantity	Shipping Container
RQK0303MGDQATL-E	3000 pcs.	φ178 mm reel, 8 mm Emboss taping

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